

What is claimed is:

1. A heat-curable adhesive composition comprising:
an ethylene-glycidyl (meth)acrylate copolymer;
a low density polyethylene;

5 an ethylene- α -olefin copolymer; and
a heat curing agent for said ethylene-glycidyl
(meth)acrylate copolymer.

10 2. A heat-curable adhesive composition of claim 1,
wherein the minimum density of said low density polyethylene
is 0.910 as measured according to ASTM D1248-84.

15 3. A heat-curable adhesive composition of any
preceding claim, wherein the maximum density of said low
density polyethylene is 0.925 as measured according to ASTM
D1248-84.

4. A heat-curable adhesive composition of any
preceding claim, wherein, in said ethylene- α -olefin
copolymer, the polymerization ratio of ethylene to α -olefin
is 90:10 to 10:90.

20 5. A heat curable adhesive composition of any
preceding claim, wherein the minimum density of said
ethylene- α -olefin copolymer is 0.850 as measured according
to ASTM D1248-84.

25 6. A heat curable adhesive composition of any
preceding claim, wherein the maximum density of said
ethylene- α -olefin copolymer is 0.909 as measured according
to ASTM D1248-84.

7. A heat-curable adhesive composition of any
preceding claim, wherein said heat curing agent is a rosin
having a carboxyl group in the molecule.

30 8. A heat-curable adhesive composition of any
preceding claim, wherein said composition is in the form of
a thin film of 5 to 80 μm in thickness.

35 9. A heat-curable adhesive composition of any
preceding claim, wherein, after post-curing, the composition
has a dielectric constant of 2.5 or less, and a dielectric
loss tangent of about 0.015 or less when measured at the

frequency of about 1 GHz.